## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)
Yeo et al.	)
Serial No.:	) Express Mail Certification
Filed:	) Label No. EV016784297US
For: ENHANCED CHIP SCALE PACKAGE FOR FLIP CHIPS	) ) )
Attorney's Docket No.: 4795-001	) )
	Raleigh, North Carolina February 19, 2002
Commissioner for Patents BOX PATENT APPLICATION	

Washington, D.C. 20231

Dear Sir:

## **CLAIM OF PRIORITY**

The applicant in this case claims priority based on a prior application filed in Singapore and identified as Singapore Patent Application No. 200106785-9 filed on November 2, 2001.

A certified copy of the Singapore application will be submitted in due course.

Respectfully submitted,

**COATS & BENNETT, P.L.L.C.** 

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